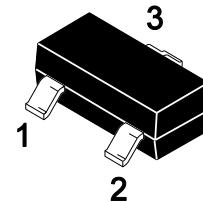




Features

- $V_{DS} = -60V$ $I_D = -2.0A$
- $R_{DS(ON)} = 200m\Omega(\text{max}) @ -10V$
- Halogen and Antimony Free

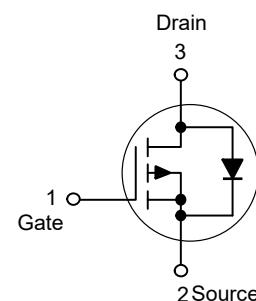
SOT-23



1. Gate 2. Source 3. Drain

Marking: S9

Schematic Diagram



Applications

- Load Switch and in PWM Applications
- Power Management

Absolute Maximum Ratings

Ratings at $T_A = 25^\circ\text{C}$ unless otherwise specified.

Parameter	Symbol	Value	Units
Drain-Source Voltage	$-V_{DS}$	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$-I_D$	2	A
Power Dissipation	P_D	1.4	W
Junction and Storage Temperature Range	T_J, T_{STG}	150, -55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ.	Units
Maximum Junction-to-Ambient	$R_{\theta JA}$	89	$^\circ\text{C}/\text{W}$



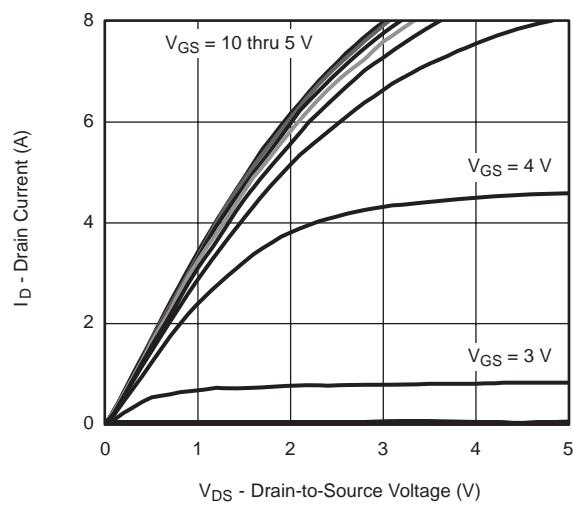
Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Units
Static Characteristics						
Drain-source breakdown voltage	$-V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = -250\mu\text{A}$	60	--	--	V
Drain to Source Leakage Current	$-I_{\text{DSS}}$	$V_{\text{DS}} = -60\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$	--	--	± 100	nA
Gate threshold voltage ^{Note1}	$-V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = -250\mu\text{A}$	1.5	--	3	V
Drain-source on-resistance ^{Note1}	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_{\text{D}} = -2\text{A}$	--	--	200	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_{\text{D}} = -1\text{A}$	--	--	400	$\text{m}\Omega$
Forward transconductance ^{Note1}	g_{FS}	$V_{\text{DS}} = -5\text{V}, I_{\text{D}} = -2\text{A}$	--	6	--	S
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	--	850	--	pF
Output Capacitance	C_{oss}		--	65	--	
Reverse Transfer Capacitance	C_{rss}		--	28	--	
Switching Characteristics						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$I_{\text{D}} = -1\text{A}, V_{\text{DD}} = -30\text{V}, V_{\text{GS}} = -10\text{V}, R_{\text{GEN}} = 3\Omega, R_{\text{L}} = 7.5\Omega$	--	7	--	ns
Turn-on rise time	t_r		--	3	--	
Turn-off delay time	$t_{\text{d}(\text{off})}$		--	28	--	
Turn-off fall time	t_f		--	5.5	--	
Total gate charge	Q_g	$V_{\text{DD}} = -30\text{V}, V_{\text{GS}} = -10\text{V}, I_{\text{D}} = -2\text{A}$	--	22	--	nC
Gate-source charge	Q_{gs}		--	2.5	--	
Gate-drain charge	Q_{gd}		--	6	--	
Source-Drain Diode characteristics						
Continuous Source-Drain Diode Current	$-I_s$	$V_{\text{GS}} = 0\text{V}, I_{\text{S}} = -2\text{A}$	--	--	1.4	A
Diode Forward voltage	$-V_{\text{DS}}$		--	--	1.2	V

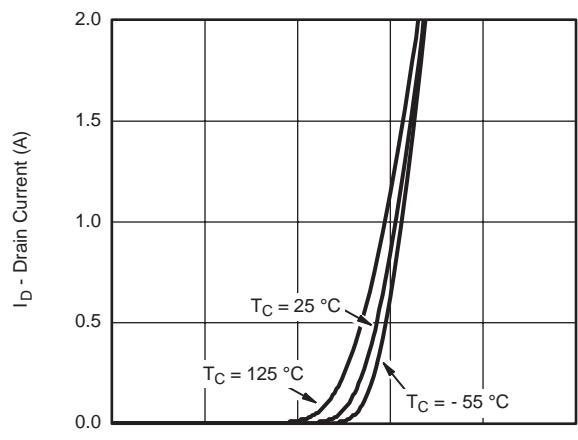
Notes: 1. Pulse test ; pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.



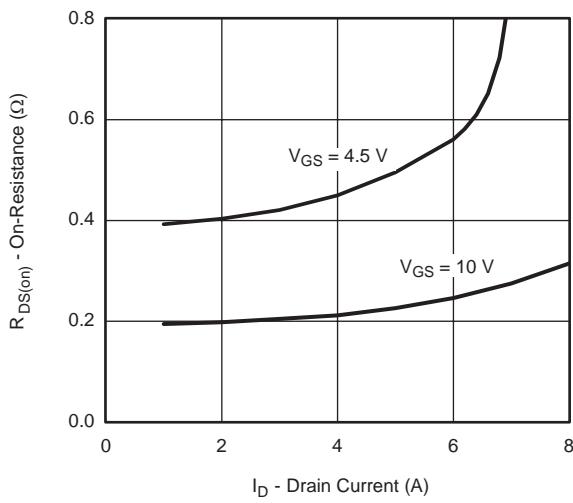
Typical Characteristic Curves



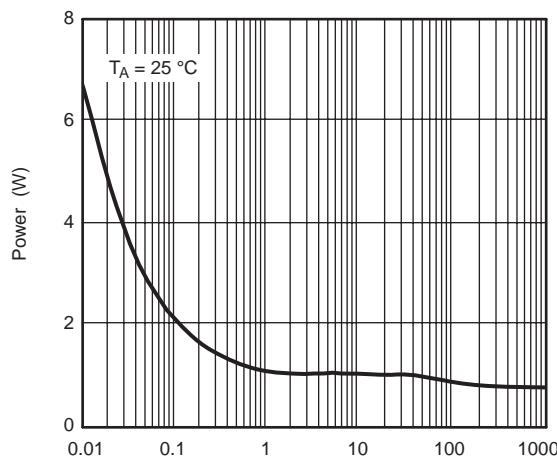
Output Characteristics



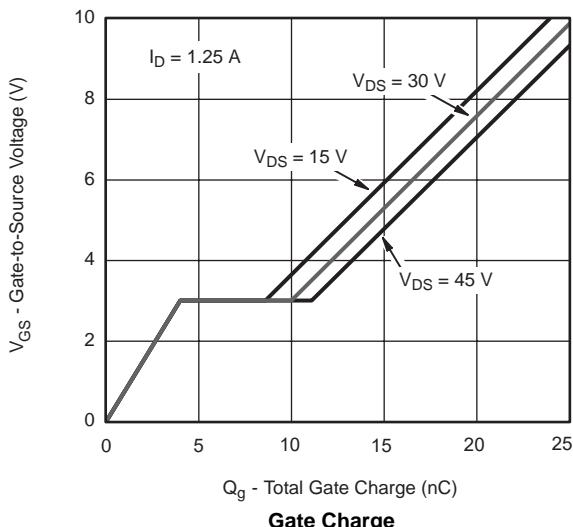
Transfer Characteristics



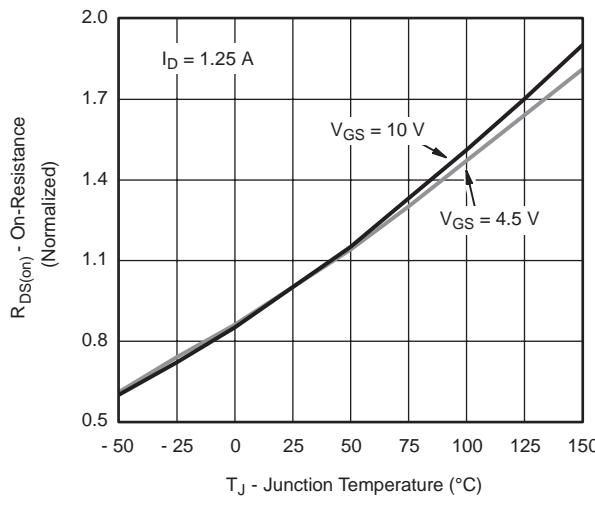
On-Resistance vs. Drain Current and Gate Voltage



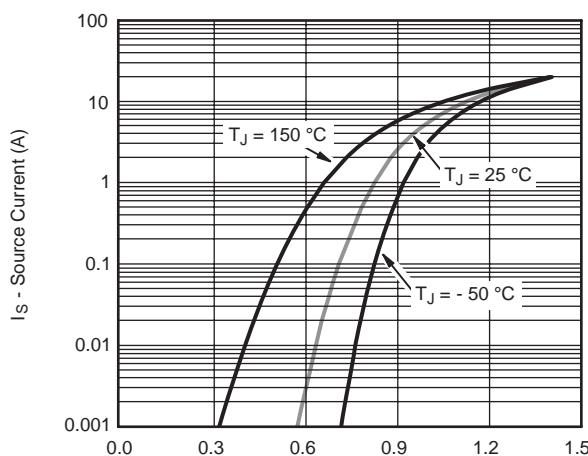
Single Pulse Power, Junction-to-Ambient



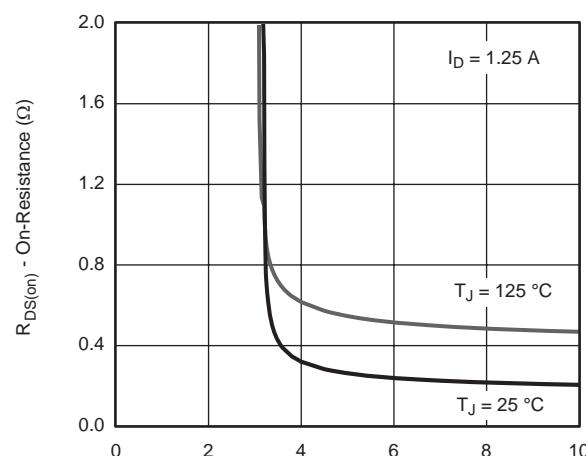
Gate Charge



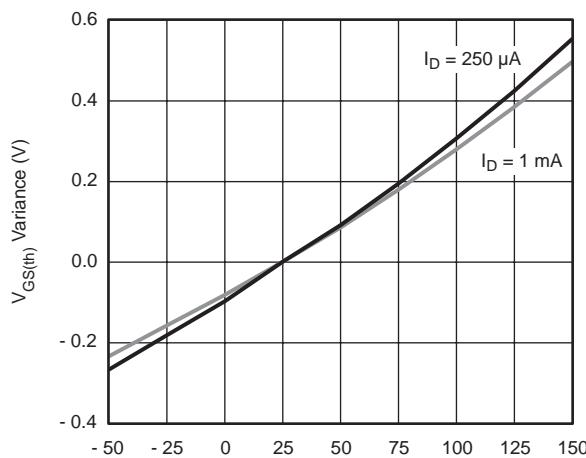
On-Resistance vs. Junction Temperature



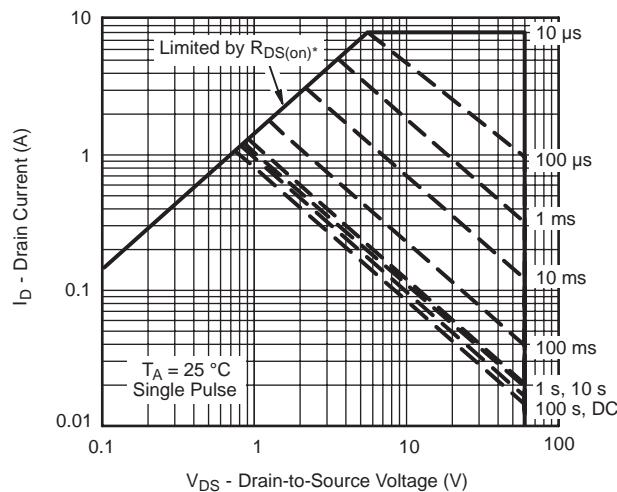
Source-Drain Diode Forward Voltage



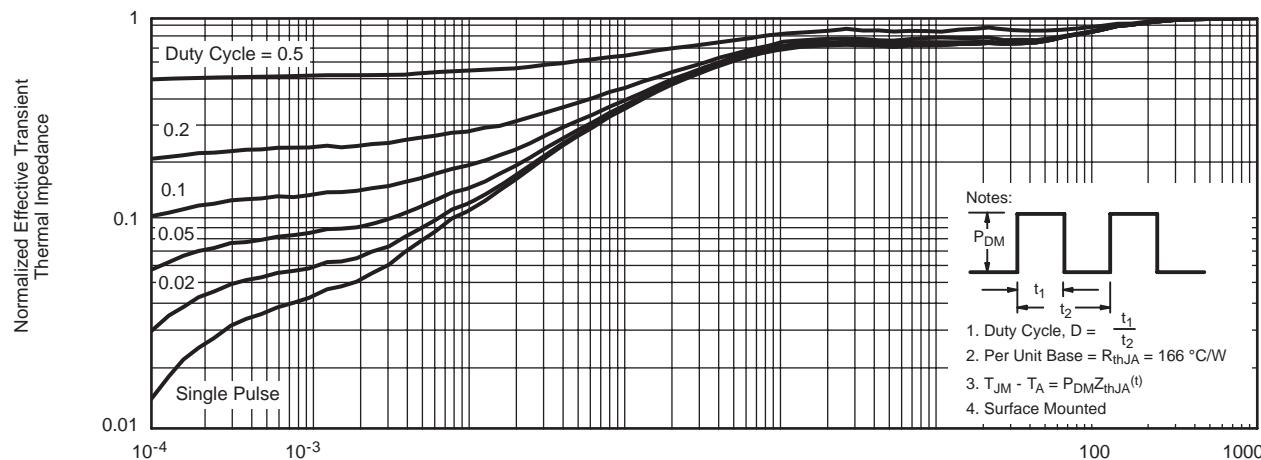
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Safe Operating Area, Junction-to-Ambient

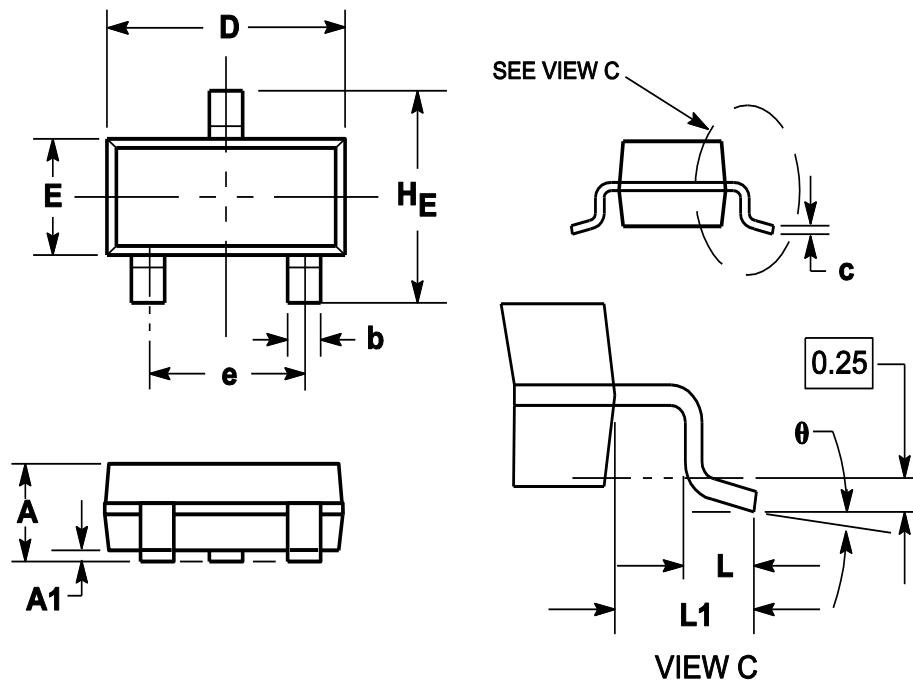


Normalized Thermal Transient Impedance, Junction-to-Ambient

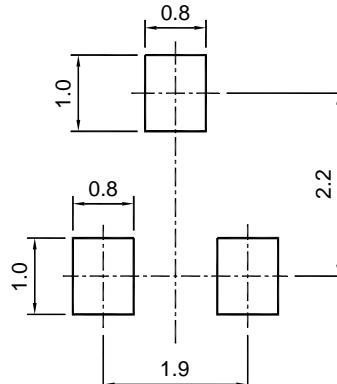


Package Outline

SOT-23



Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.900	1.025	1.150
A1	0.000	0.050	0.100
b	0.300	0.400	0.500
c	0.080	0.115	0.150
D	2.800	2.900	3.000
E	1.200	1.300	1.400
H _E	2.250	2.400	2.550
e	1.800	1.900	2.000
L1	0.550REF		
L	0.300		0.500
θ	0°		8°



SOT-23 (TO-236)

Recommended soldering pad

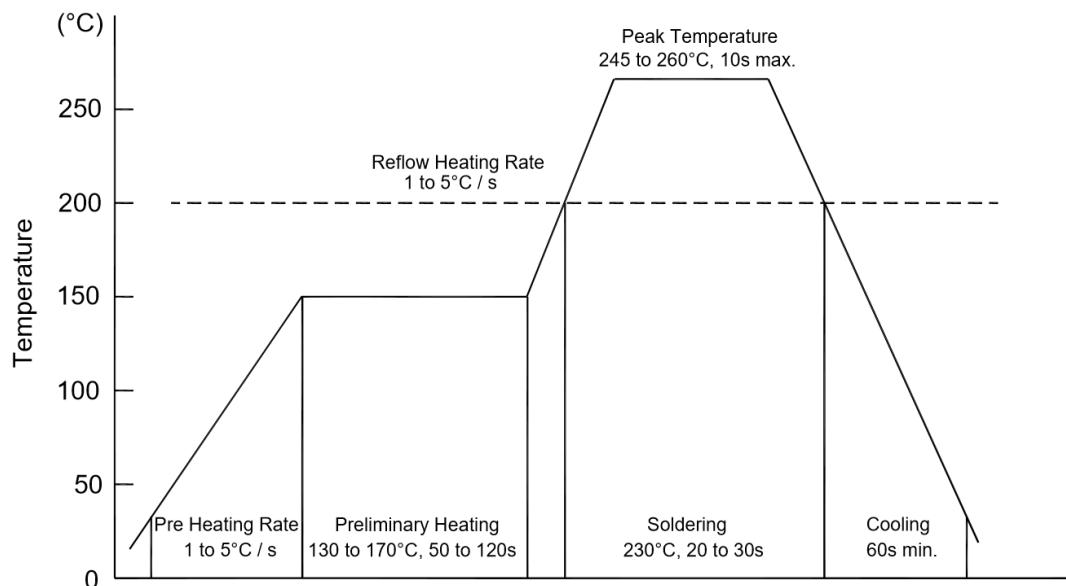
Ordering Information

Device	Package	Shipping
PJM2309PSA	SOT-23	3000PCS/Reel&Tape



Conditions of Soldering And Storage

◆ Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

◆ Conditions of hand soldering

- Temperature: 370 °C
- Time: 3s max.
- Times: one time

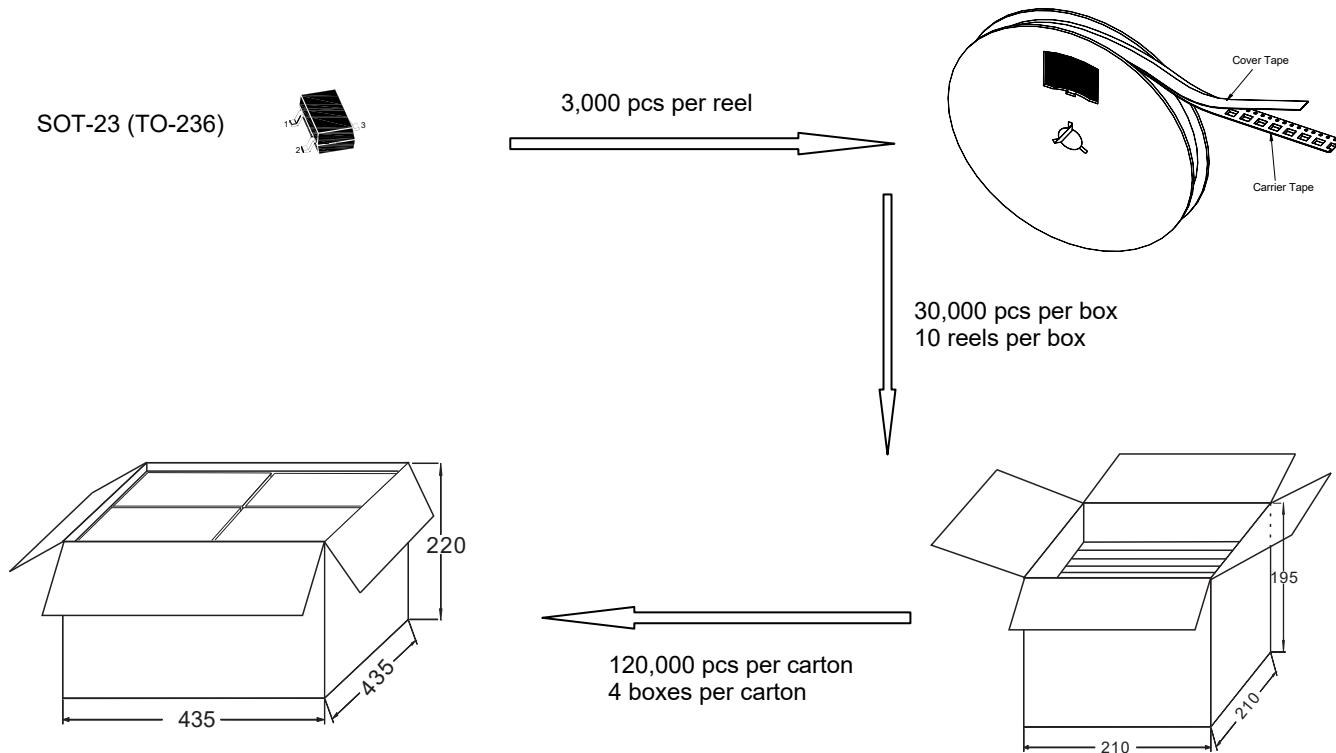
◆ Storage conditions

- **Temperature**
5 to 40 °C
- **Humidity**
30 to 80% RH
- **Recommended period**
One year after manufacturing

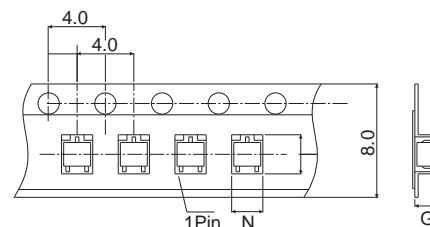
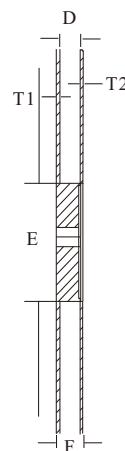
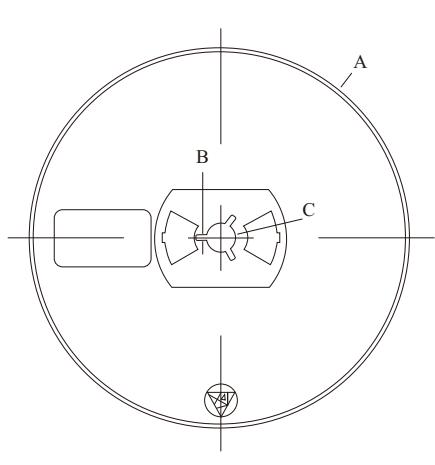


Package Specifications

- The method of packaging



◆ Embossed tape and reel data



Tape (8mm)

Symbol	Value (unit: mm)
A	$\varnothing 177.8 \pm 1$
B	2.7 ± 0.2
C	$\varnothing 13.5 \pm 0.2$
E	$\varnothing 54.5 \pm 0.2$
F	12.3 ± 0.3
D	$9.6 +2/-0.3$
T1	1.0 ± 0.2
T2	1.2 ± 0.2
N	3.15 ± 0.1
G	1.25 ± 0.1

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